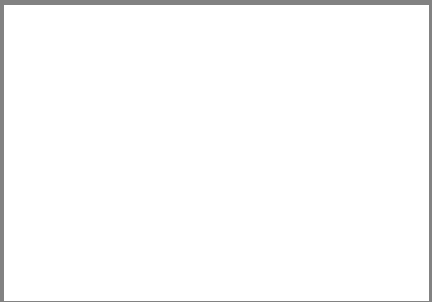




SEMICELL DIODES

SKN 6002

$I_F = 6000\text{ A}$
 $V_{RRM} = 600\text{ V}$
Size: diameter: 47,5 mm
Package: tray

Features

Typical Applications

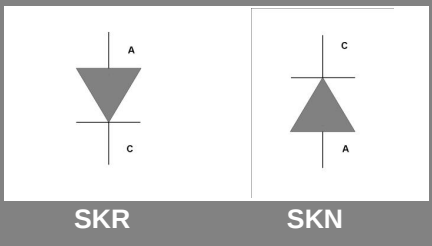
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Absolute Maximum Ratings			
Symbol	Conditions	Values	Units
V_{RRM}	$T_{vj} = 25\text{ °C}, I_R = 2\text{ mA}$	600	V
$I_{F(AV)}$	$T_{vjmax} = 150\text{ °C}$	6000	A
I^2t	$T_{vjmax} = 165\text{ °C}, 10\text{ ms, half sine wave}$	60000	A^2s
I_{FSM}	$T_{vj} = 25\text{ °C}, 10\text{ ms, half sine wave}$		A
	$T_{vjmax} = 165\text{ °C}, 10\text{ ms, half sine wave}$		A
T_{vjmax}		+ 165	°C

Electrical Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
I_R	$T_{vj} = 25\text{ °C}, V_{RRM}$			2	mA
	$T_{vj} = 165\text{ °C}, V_{RRM}$			55	mA
V_F	$T_{vj} = 25\text{ °C}, I_F = 14000\text{ A}$		1,25		V
	$T_{vj} = \text{°C}, I_F = A$				V
$V_{(TO)}$	$T_{vj} = \text{°C},$				V
r_T	$T_{vj} = \text{°C},$				mΩ
t_{rr}	$T_{vj} = 25\text{ °C}, \pm 1\text{ A}$		10		µs

Thermal Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
T_{vj}					°C
T_{stg}					°C
T_{solder}	min				°C
T_{solder}	min				°C
					K / W

Mechanical Characteristics		
Parameter		Units
raster size		mm
Area total		mm ²
Chips / Tray		pcs
Anode metallisation		
Cathode metallisation		
wire bond		



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